



## Material Content Data Sheet



<b>Sales Product Name</b>	TLS810A1LD V33			<b>Issued</b>	1. August 2018			
<b>MA#</b>	MA001829506							
<b>Package</b>	PG-TSON-10-2			<b>Weight*</b>	31.70 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.996	3.14	3.14	31416	31416
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		105	
	non noble metal	zinc	7440-66-6	0.013	0.04		418	
	non noble metal	iron	7439-89-6	0.265	0.84		8369	
wire	non noble metal	copper	7440-50-8	10.773	33.98	34.87	339808	348700
	non noble metal	copper	7440-50-8	0.017	0.05	0.05	546	546
	organic material	carbon black	1333-86-4	0.038	0.12		1185	
encapsulation	plastics	epoxy resin	-	1.935	6.10		61045	
	inorganic material	silicondioxide	60676-86-0	16.816	53.06	59.28	530443	592673
leadfinish	non noble metal	tin	7440-31-5	0.370	1.17	1.17	11674	11674
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2027	2027
glue	plastics	epoxy resin	-	0.103	0.32		3241	
	noble metal	silver	7440-22-4	0.308	0.97	1.29	9723	12964
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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